

**S/N 09/733,289**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Xiao-Chun Mu et al.	Examiner: DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit: 2814
Filed:	December 8, 2000	Docket: 884.798US1
Title:	MICROELECTRONIC PACKAGE HAVING AN INTEGRATED HEAT SINK AND BUILD-UP LAYERS	

**COMMUNICATION CONCERNING RELATED APPLICATION(S)**

**MS Amendment**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/884595	June 18, 2001	884.D51US1	MICROELECTRONIC SUBSTRATES WITH INTEGRATED DEVICES
10/964238 7,078,788	October 13, 2004	884.D51US2	MICROELECTRONIC SUBSTRATES WITH INTEGRATED DEVICES


Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

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By

  
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**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 25<sup>th</sup> day of February, 2008.

JUDY DENT  
Name

  
Signature